

**Title: Medium board, base board with medium board and structure part and method for producing medium board****Application Number** 200410030164 **Application Date** 2004.03.19**Publication Number** 1533227 **Publication Date** 2004.09.29**Priority Information****International Classification** H01L25/00;H05K1/02;H05K1/18;H05K3/00;H05K3/46**Applicant(s) Name** NGK Spark Plug Co., Ltd.**Address****Inventor(s) Name** Imai Takaji;Kuroda Masao;Sugimoto Yasuhiro**Patent Agency Code** 11038 **Patent Agent** wang yonggang**Abstract**

An intermediate board comprising: an intermediate board body having first and second faces wherein a semiconductor device is to be mounted on at least one of said first and second faces, said semiconductor device having a coefficient of thermal expansion that is equal to or larger than 2.0 ppm/ DEG C. and smaller than 5.0 ppm/ DEG C., and having surface mount terminals, said intermediate board body having a plurality of through holes through which said first and second faces communicate with each other, said intermediate board body containing an inorganic insulating material; and a plurality of conductor columns filling said through holes and containing a conductive metal, said conductor columns being to be connected with said surface mount terminals.

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